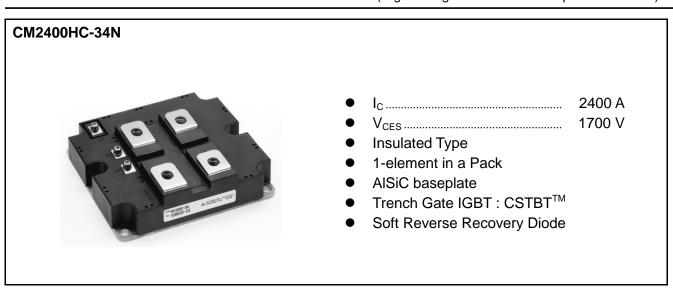


< High Voltage Insulated Gate Bipolar Transistor: HVIGBT >

CM2400HC-34N

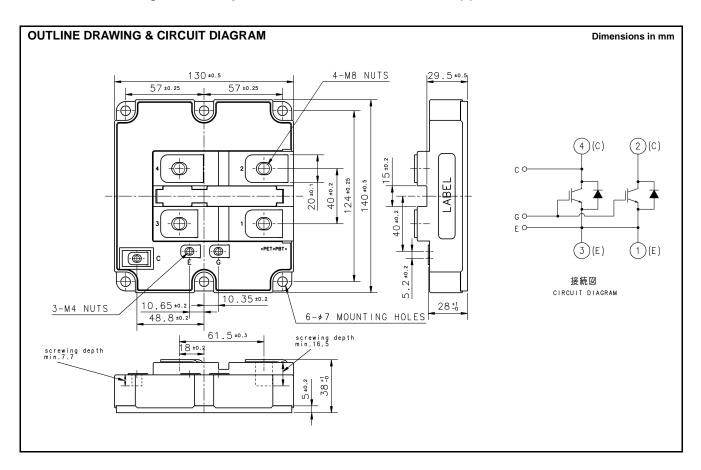
HIGH POWER SWITHCHING USE INSULATED TYPE

4th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules



APPLICATION

Traction drives, High Reliability Converters / Inverters, DC choppers



Publication Date: Feb.2015

(HVM-1035-D)

CM2400HC-34N

HIGH POWER SWITHCHING USE INSULATED TYPE

4th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

MAXIMUM RATINGS

Symbol	Item	Conditions	Ratings	Unit
V _{CES}	Collector-emitter voltage	$V_{GE} = 0V, T_j = 25^{\circ}C$	1700	V
V_{GES}	Gate-emitter voltage	$V_{CE} = 0V$, $T_j = 25$ °C	± 20	V
Ic	Collector current	DC, $T_c = 75$ °C	2400	Α
I _{CRM}	Collector current	Pulse (Note 1)	4800	Α
I _E	Emitter current (Note 2)	DC	2400	Α
I _{ERM}	Emitter current (Note 2)	Pulse (Note 1)	4800	Α
P _{tot}	Maximum power dissipation (Note 3)	T _c = 25°C, IGBT part	13100	W
V _{iso}	Isolation voltage	RMS, sinusoidal, f = 60Hz, t = 1 min.	4000	V
Tj	Junction temperature		− 40 ~ + 150	°C
T_jop	Operating junction temperature		− 40 ~ + 125	°C
T _{stg}	Storage temperature		− 40 ~ + 125	°C
t _{psc}	Short circuit pulse width	$V_{CC} = 1200V, V_{CE} \le V_{CES}, V_{GE} = 15V, T_j = 125^{\circ}C$	10	μs

ELECTRICAL CHARACTERISTICS

Symbol	Item	Conditions		Limits			Unit
Symbol	item			Min	Тур	Max	Offic
	Collector outoff ourrent	V V V 0V	$T_j = 25^{\circ}C$	_	_	8.0	mA
I _{CES}	Collector cutoff current	$V_{CE} = V_{CES}, V_{GE} = 0V$	$T_{j} = 125^{\circ}C$	_	6.0	16.0	mA
$V_{GE(th)}$	Gate-emitter threshold voltage	$V_{CE} = 10 \text{ V}, I_{C} = 240 \text{ mA}, T_{j} = 25^{\circ}\text{C}$		6.0	7.0	8.0	V
I _{GES}	Gate leakage current	$V_{GE} = V_{GES}$, $V_{CE} = 0V$, $T_j = 25$ °C		_	_	0.5	μΑ
C _{ies}	Input capacitance	\\ 10\\\\\ 0\\\ f 100\\\\		_	352		nF
Coes	Output capacitance	$V_{CE} = 10 \text{ V}, V_{GE} = 0 \text{ V}, f = 100 \text{ kHz}$ $T_j = 25^{\circ}\text{C}$		_	19.2		nF
C _{res}	Reverse transfer capacitance			_	5.6	_	nF
Q_G	Total gate charge	$V_{CC} = 850V$, $I_C = 2400A$, $V_{GE} = \pm 15V$, $T_j = 25$ °C		_	24.5	_	μC
V	Collector-emitter saturation voltage	$I_C = 2400 \text{ A}^{\text{(Note 4)}}$ $V_{GE} = 15 \text{ V}$	T _j = 25°C	_	2.15	2.80	V
V _{CEsat}			$T_{j} = 125^{\circ}C$	_	2.40	_	V
t _{d(on)}	Turn-on delay time	V _{CC} = 850 V. I _C = 2400 A. V _{GE} = ±15 V		_	_	1.50	μs
t _r	Turn-on rise time $R_{G(on)} = 0.7 \Omega$, $T_j = 125^{\circ}C$, $L_s = 100 \text{ nH}$		_	_	0.70	μs	
E _{on(10%)}	Turn-on switching energy (Note 5)	Inductive load		_	640	_	mJ
t _{d(off)}	Turn-off delay time	$V_{CC}=850~V,~I_C=2400~A,~V_{GE}=\pm15~V$ $R_{G(off)}=1.6~\Omega,~T_j=125^{\circ}C,~L_s=100~nH$ Inductive load		_	_	3.00	μs
t _f	Turn-off fall time			_	_	0.60	μs
E _{off(10%)}	Turn-off switching energy (Note 5)			_	840	_	mJ
	(Note 2)	I _E = 2400 A ^(Note 4)	T _j = 25°C	_	2.60	3.30	
V _{EC}	Emitter-collector voltage (Note 2)	$V_{GE} = 0 V$	T _j = 125°C	_	2.30	_	V
t _{rr}	Reverse recovery time (Note 2)	$V_{CC} = 850 \text{ V}, I_{C} = 2400 \text{ A}, V_{GE} = \pm 15 \text{ V}$,	_	_	1.50	μs
Q _{rr}	Reverse recovery charge (Note 2)	$R_{G(on)} = 0.7 \Omega$, $T_j = 125$ °C, $L_s = 100 \text{ nH}$		_	620	_	μC
E _{rec(10%)}	Reverse recovery energy ^{(Note 2), (Note 5)}	Inductive load		_	380	_	mJ

< High Voltage Insulated Gate Bipolar Transistor: HVIGBT >

CM2400HC-34N

HIGH POWER SWITHCHING USE INSULATED TYPE

4th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

THERMAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
Symbol			Min	Тур	Max	Uill
$R_{th(j-c)Q}$	Thermal resistance	Junction to Case, IGBT part	_	_	9.5	K/kW
$R_{th(j-c)D}$	rnermai resistance	Junction to Case, FWDi part	_	_	21.0	K/kW
R _{th(c-s)}	Contact thermal resistance	Case to heat sink, λ _{grease} = 1W/m·k, D _(c-s) = 100μm	1	8.0		K/kW

MECHANICAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			I limit
			Min	Тур	Max	Unit
M_t		M8 : Main terminals screw	7.0	_	20.0	N⋅m
Ms	Mounting torque	M6: Mounting screw	3.0	_	6.0	N⋅m
M_t		M4 : Auxiliary terminals screw	1.0	_	3.0	N⋅m
m	Mass		I	0.8		kg
CTI	Comparative tracking index		600	_		
d _a	Clearance		19.5	_		mm
ds	Creepage distance		32.0	_	ı	mm
L _{P CE}	Parasitic stray inductance	IGBT part	1	16	1	nΗ
R _{CC'+EE'}	Internal lead resistance	IGBT part , T _C = 25°C		0.14	_	mΩ

Note 1. Pulse width and repetition rate should be such that junction temperature (T_j) does not exceed T_{jopmax} rating.

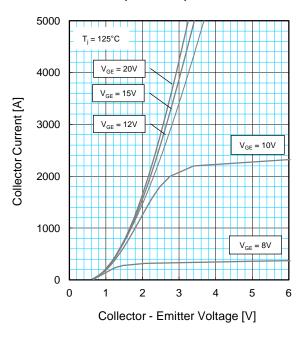
Note 2. The symbols represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWD_i).

Note 3. Junction temperature (T_j) should not exceed T_{jmax} rating (150°C).

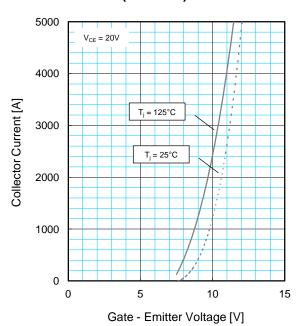
Note 4. Pulse width and repetition rate should be such as to cause negligible temperature rise.

Note 5. $E_{on(10\%)}$ / $E_{off(10\%)}$ / $E_{rec(10\%)}$ are the integral of 0.1 V_{CE} x 0.1 I_{C} x dt.

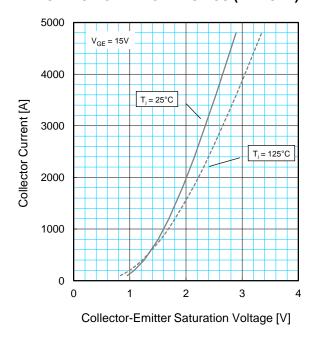
OUTPUT CHARACTERISTICS (TYPICAL)



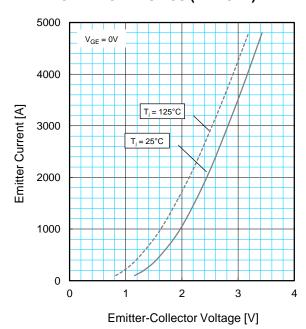
TRANSFER CHARACTERISTICS (TYPICAL)



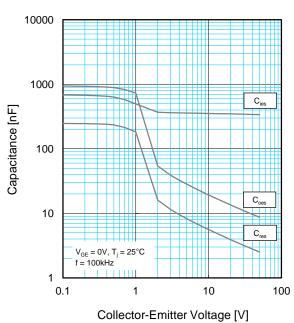
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



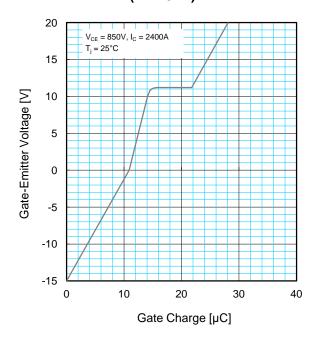
FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)



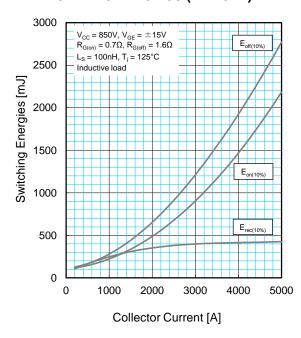
CAPACITANCE CHARACTERISTICS (TYPICAL)



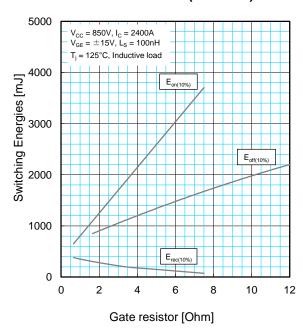
GATE CHARGE CHARACTERISTICS (TYPICAL)



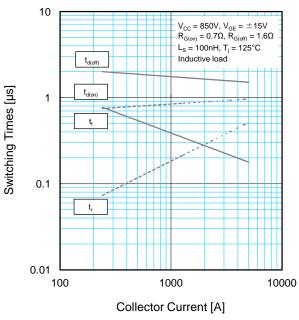
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



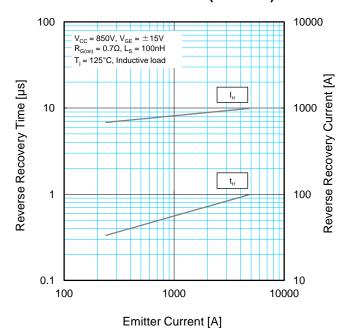
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



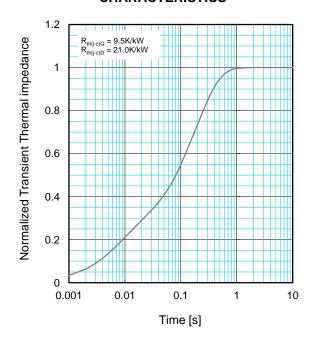
HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)



FREE-WHEEL DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)

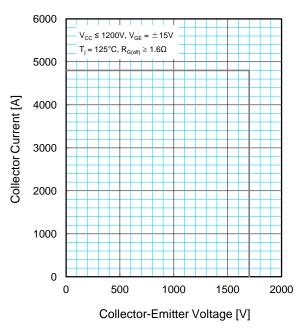


TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS

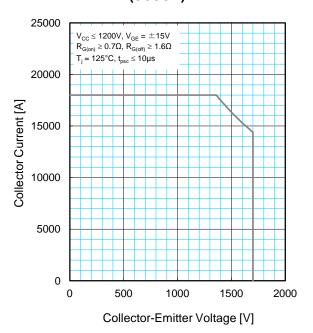


$Z_{th(j-c)}(t) = \sum_{i=1}^{n} R_{i} \left\{ 1 - exp^{\left(-\frac{t}{\tau_{i}}\right)} \right\}$							
	1	2	3	4			
R _i [K/kW]	0.0096	0.1893	0.4044	0.3967			
t _i [sec]	0.0001	0.0058	0.0602	0.3512			

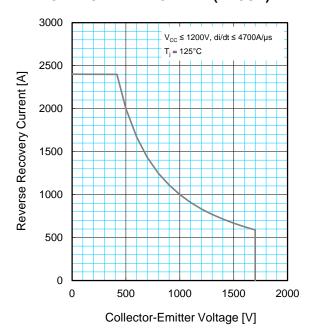
REVERSE BIAS SAFE OPERATING AREA (RBSOA)



SHORT CIRCUIT SAFE OPERATING AREA (SCSOA)



FREE-WHEEL DIODE REVERSE RECOVERY SAFE OPERATING AREA (RRSOA)



4th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

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